

CLAIMS

1. A method for manufacturing a printed wiring board, including the steps of: forming a thermosetting resin layer so as to fill spaces between circuit patterns formed on the printed wiring board; heating and curing the resin layer in a reduced pressure chamber in which a pressure is reduced, while a smoothing plate is pressed against the resin layer; and then polishing said cured resin layer covering said circuit patterns, thereby exposing said circuit patterns,

said step of heating and curing said resin layer in said reduced pressure chamber, comprising the following steps being successively performed:

maintaining said resin layer at a non-curable temperature to prevent the resin layer from curing in a state where said resin layer is pressed via said smoothing plate in said reduced pressure chamber (step1);

heating said resin layer in said pressed state to a curing temperature at which said resin layer is cured (step 2);

introducing outside air into said reduced pressure chamber with said pressed state and said curing temperature maintained (step 3);

reducing the pressure applied to said smoothing plate with said curing temperature maintained (step 4); and

cooling said resin layer (step 5).

2. The method for manufacturing a printed wiring board according to claim 1, wherein in said step 1, the applied pressure is increased in stages.

3. The method for manufacturing a printed wiring board according to claim 1 or claim 2, wherein said resin layer is formed by having a liquid resin adhere to said printed wiring board so as to fill spaces between said circuit patterns, and wherein a metallic foil with a roughened surface facing said resin layer is superposed on the resin layer.

4. The method for manufacturing a printed wiring board according to claim 1 or claim 2, wherein said resin layer is formed by having a semi-cured resin sheet superposed on the printed wiring board, and wherein a metallic foil with a roughened surface facing said resin layer is superposed on the resin layer.

5. The method for manufacturing a printed wiring board according to claim 3 or claim 4, wherein said metallic foil is formed with a metal of a different kind from said circuit patterns.